Features

- Maximum substrate size: 6” x 6”
- Minimum substrate size: 6 x 6 mm²
- Substrate thickness: 0 to 6 mm
- Encoder resolution: 20 nm
- Optical system including highly reflective mirrors and DMDTM
- Real-time air-gauge autofocus with dynamic range of 80 µm
- Camera system for substrate inspection, automatic alignment, and basic measurement functions
- Basic gray scale exposure mode with 128 intensity levels
- Conversion software for DXF, CIF, GDSII, and Gerber files for binary exposures and BMP, STL, and ASCII files for gray scale
- LED Illumination Module (390nm)
- Minimum structure size [µm]: 1
- Address grid [nm]: 50
- Edge roughness [3σ, nm]: 100
- Line width uniformity [3σ, nm]: 200
- Alignment Accuracy [3σ, nm]: 200
- Write speed [mm2/minute]: 50
- Maximum write area [mm x mm]: 125 x 125

Heidelberg UPG501